

HD Express®

PCIe® GEN 6 BACKPLANE INTERCONNECT SYSTEM

The HD Express® is a high-density, high-performance interconnect system designed to meet and exceed PCIe® Gen 6 electrical and mechanical requirements for high-end 85Ω architectures.

- PCIe® Gen 6
- Price and performance scalability
- Modular construction with integrated guidance
- Highest density
- 85Ω impedance



FEATURES

- 85Ω impedance
- Ground structure on all 4 sides of the mating beams of each differential pair
- Highest density
- Scalable design
- 13.8 Mil Drill-Compliant Pin
- Beam on blade
- Press-fit
- Die-cast guide module

BENEFITS

- Specifically designed to support PCIe® Gen 6 links
- Provides high signal isolation performance
- Highest density backplane product in the market
- Single Wafer design utilizing traditional design elements
- Proven press-fit technology
- Provides a complete solution for customer's unique requirements
- For additional margin and overall system cost savings
- Robust guidance features integrated into the connector design

TECHNICAL INFORMATION

MATERIAL

- Contact Finish Area: Gold
- Contact Base Metal: High performance Copper Alloy
- Housings: Glass Reinforced Polyester (LCP)

ELECTRICAL PERFORMANCE

- Rated Signal Contact Current Rating: TBD (UL Agency)
- Rated Voltage <30VAC (RMS) (UL Agency)
- Dielectric Withstanding Voltage: TBD
- Contact Resistance Change: 10mΩ max.

MECHANICAL PERFORMANCE

- Wiping Length : TBD
- Gathering Ability: TBD
- Durability: TBD

APPROVALS AND CERTIFICATIONS

- UL94V-0

PACKAGING

- PVC Trays (ESD)

ENVIRONMENTAL

- Operating Temperature Range: -40°C to 105°C

PART NUMBERS

Description	Part Numbers
HD Express BMA 4Pr 8 pos	036-41C1-0BV
HD Express DC 4Pr 8 pos	039-41C0-10V

Find part number details using the search box on www.amphenol-cs.com

SPECIFICATIONS

- TBD

TARGET MARKETS/APPLICATIONS



Servers
Storage
Supercomputers